# APPENDIX A FIBER ENDFACE INSPECTION CRITERIA AFTER POLISHING

#### **BARE FIBER - BACK-LIT**

## PERFECT FIBER Top View ACCEPTABLE **Oblique View** Accept. Free from cracks, scratches, edge chips, hackles, pits and other anomalies and Photo Image core is clearly discerned. EDGE CHIPS ACCEPTABLE Top View **Oblique View** Cladding Core Acceptable if chip maximum dimension < 3% of fiber diameter and number of</p> chips $\leq$ 3. Photo Image Chip HACKLE Top View **REJECT Oblique View** Surface irregularity due to improper cleaving. Reject/re-cleave. Photo Image Reject for splice connection. May be fixable by polishing if used in connector.

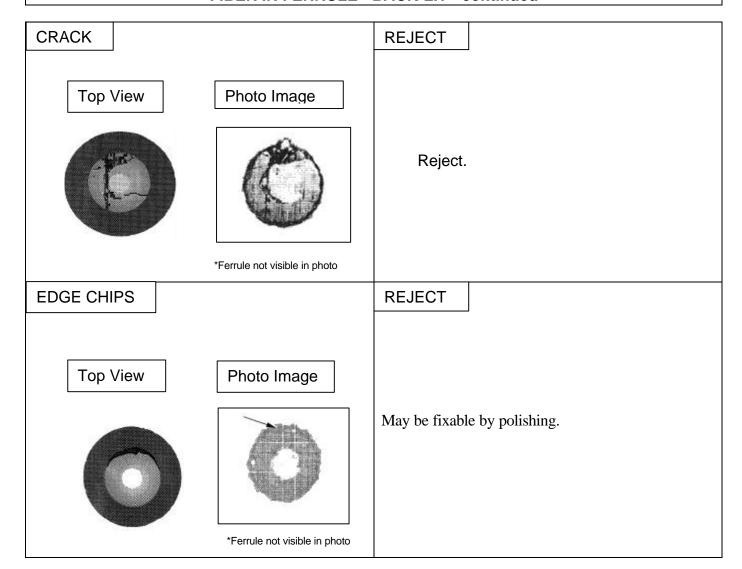
#### **BARE FIBER - BACK-LIT - continued**

# **SCRATCHES** Top View **REJECT Oblique View** Reject/Repolish. Reject if performance is affected. Photo Image CRACK **REJECT** Top View Oblique View Any cracks are rejectable. Photo Image CRACK (Below Surface) **REJECT Oblique View Cut Away View** Any cracks are rejectable. Top View Most often only detected by back-lit operation.

#### FIBER IN FERRULE BACK-LIT

## PERFECT FIBER **ACCEPT** Top View Free from cracks, scratches, voids in **Ferrule** the adhesive bond, and other Cladding anomalies; and concentric within the performance requirements. Core Adhesive bond line SURFACE PITS **REJECT** Photo Image Top View Reject/Repolish if in core or cladding. **SCRATCHES REJECT** Photo Image Top View Reject/Repolish if in core.

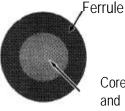
### FIBER IN FERRULE - BACK-LIT - continued



#### FIBER IN FERRULE - DIRECT-LIT, NO CORE ILLUMINATION

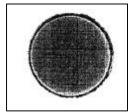
#### **PERFECT**

Top View



Core and Cladding

#### Photo Image



\* Ferrule not visible in photo

#### **ACCEPT**

Free from cracks, scratches, edge chips, hackles, pits, and other anomalies; and concentric within the performance requirements.

Note: Cracks may be invisible without core illumination.

#### SURFACE PITS

Top View

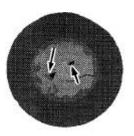


Photo Image



\* Ferrule not visible in photo

#### REJECT

Reject/Repolish if in core or cladding.

Confirm by backlighting.

#### **SCRATCHES**

Top View



#### REJECT

Reject/Repolish.

#### **EPOXY**

Top View

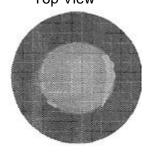
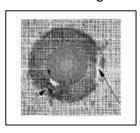


Photo Image



\* Ferrule not visible in photo

#### **REJECT**

Reject if epoxy is on core, cladding or ferrule. May be fixable by repolishing.

# APPENDIX B - TEST METHODS FOR THE VERIFICATION OF OPTICAL FIBER FABRICATION PROCESSES

The following fiber optic test procedures should be considered for all optical fiber cable assemblies, splices, and/or connectors, as applicable:

EIA-455-1 (FOTP 1)	Cable Flexing for Fiber Optic Interconnection Devices	
EIA-455-3 (FOTP 3)	Procedure to Measure Temperature Cycling Effects on Optical Fibers, Optical Cable, and Other Passive Fiber Optic Components.	
EIA-455-4 (FOTP 4)	Fiber Optic Connector/Component Temperature Life.	
EIA-455-5 (FOTP 5)	Humidity Test Procedure for Fiber Optic Connecting Devices	
EIA-455-6 (FOTP 6)	Cable Retention Test Procedure for Fiber Optic Cable Interconnecting Devices	
EIA-455-11 (FOTP 11)	Vibration Test Procedure for Fiber Optic Connecting Devices and Cable	
EIA-455-12 (FOTP 12)	Fluid Immersion Test for Fiber Optic Components	
EIA-455-13 (FOTP 13)	Visual and Mechanical Inspection of Fiber, Cables, Connectors etc.	
EIA-455-14 (FOTP 14)	Fiber Optic Shock Test (Specified Pulse)	
EIA-455-15 (FOTP 15)	Altitude Immersion	
EIA-455-16 (FOTP 16)	Salt Spray	
EIA-455-17 (FOTP 17)	Maintenance Aging of Fiber Optic Connectors and Terminated Cable Assemblies	
EIA-455-21 (FOTP 21)	Mating Durability for Fiber Optic Interconnecting Devices	
EIA-455-25 (FOTP 25)	Repeated Impact Testing of Fiber Optic Cables and Cable Assemblies	
EIA-455-26 (FOTP 26)	Crush Resistance of Fiber Optic Interconnecting Devices	
EIA-455-33 (FOTP 33)	Fiber Optic Cable Tensile Loading and Bending Test	
EIA-455-34 (FOTP 34)	Interconnection Device Insertion Loss Test	
EIA-455-36 (FOTP 36)	Twist Test for Fiber Optic Connecting Devices	
EIA-455-37 (FOTP 37)	Low or High Temperature Bend Test for Fiber Optic Cable	
EIA-455-39 (FOTP 39)	Fiber Optic Cable Water Wicking Test	
EIA-455-41 (FOTP 41)	Compressive Loading Resistance of Fiber Optic Cables	
EIA-455-42 (FOTP 42)	Optical Crosstalk in Fiber Optic Components	

EIA-455-53 (FOTP 53)	Attenuation by Substitution Measurement for Multi-mode Graded-Index Optical Fibers or Fiber Assemblies Used in Long Length Communication Systems	
EIA-455-57 (FOTP 57)	Optical Fiber End Preparation and Examination	
EIA-455-59 (FOTP 59)	Measurement of Fiber Point Defects using an Optical Time Domain Reflectometer	
EIA-455-60 (FOTP 60)	Measurement of Fiber or Cable Length Using an OTDR	
EIA-455-61 (FOTP 61)	Measurement of Fiber or Cable Attenuation Using an OTDR	
EIA-455-62 (FOTP 62)	Measurement of Optical Fiber Macrobend Attenuation	
EIA-455-69 FOTP 69)	Test Procedure for Evaluation of the Effect of Minimum and Maximum Exposure Temperatures on the Optical Fiber	
EIA-455-85 (FOTP 85)	Fiber Optic Cable Twist Test	
EIA-455-88 (FOTP 88)	Fiber Optic Cable Bend Test	
EIA-455-91 (FOTP 91)	Fiber Optic Cable Twist-Bend Test	
EIA-455-95 (FOTP 95)	Absolute Optical Power Test for Optical Fibers and Cables	
EIA-455-96 (FOTP 96)	Fiber Optic Cable Long-Term Storage Temperature Test for Extreme Environments	
EIA-455-98 (FOTP 98)	Fiber Optic Cable External Freezing Test	
EIA-455-171 (FOTP 171)	Attenuation by Substitution Measurement for Short-Length Multi- mode Graded-Index and Single-Mode Optical Fiber Cable Assemblies	
NRL/MR/6505-92-6963	Procedure for Measuring Radiation-Induced Attenuation in Optical Fibers and Optical Cables	

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